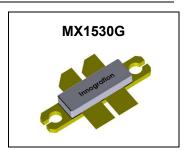
## 300W, 28V High Power RF LDMOS FETs

### **Description**

The MX1530G is a 300-watt capable, highly rugged, unmatched, push pull LDMOS FET, designed for wide-band commercial and industrial applications with frequencies 200 to 700MHz.



Typical Performance (On Innogration fixture with device soldered):

MX1530G Vgs=2.4V Vds=28V Idq=150mA CW								
Freq(MHz)	Psat(dBm)	Psat(W)	IDS(A)	Pin(dBm)	Gain(dB)	Eff(%)	2nd(dBc)	3rd(dBc)
400	55.07	321.37	18.25	36.16	18.91	62.89	-20.3	-36.7
420	54.95	312.61	17.26	35.94	19.01	64.68	-20.6	-40.5
440	55.3	338.84	17.85	35.75	19.55	67.80	-22.1	-42.5
460	55.04	319.15	16.57	36	19.04	68.79	-24.9	-44.6
480	55	316.23	15.66	36.07	18.93	72.12	-28.7	-46.9
500	54.78	300.61	14.67	37.44	17.34	73.18	-32.8	-46.8

### **Features**

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- · Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

### **Applications**

- 225-512MHz (ultra shortwave communication)
- 470-700MHz (TV UHF)

#### **Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
DrainSource Voltage	V <sub>DSS</sub>	+65	Vdc
GateSource Voltage	V <sub>GS</sub>	-10 to +10	Vdc
Operating Voltage	V <sub>DD</sub>	+28	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	T₃	+225	°C

### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Doug	0.07	00/14/
T <sub>C</sub> = 85°C, Pout=300W,CW Test	R⊕JC	0.27	°C/W

### **Table 3. ESD Protection Characteristics**

Test Methodology	Class	
Human Body Model (per JESD22A114)	Class 2	

Document Number: MX1530G Product Datasheet V1.0

**Table 4. Electrical Characteristics** ( $T_A = 25$  °C unless otherwise noted)

Characteristic	Cumbal	Min	Tun	Mov	Linit
Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics (per half section)					
Drain-Source Voltage	.,	0.5			.,
V <sub>GS</sub> =0, I <sub>DS</sub> =1.0mA	V <sub>(BR)DSS</sub> 65				V
Zero Gate Voltage Drain Leakage Current				_	
$(V_{DS} = 75V, V_{GS} = 0 V)$	I <sub>DSS</sub>			1	μΑ
Zero Gate Voltage Drain Leakage Current				1	μА
$(V_{DS} = 28 \text{ V}, V_{GS} = 0 \text{ V})$	I <sub>DSS</sub>				
GateSource Leakage Current	I <sub>GSS</sub>			1	μА
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$					
Gate Threshold Voltage					,,
$(V_{DS} = 28V, I_D = 400 \mu A)$	V <sub>GS</sub> (th)		2	<del></del>	V
Gate Quiescent Voltage	$V_{GS(Q)}$		2.4		
(V <sub>DD</sub> = 28V, I <sub>D</sub> = 150 mA, Measured in Functional Test)					V

Load Mismatch (In Innogration Test Fixture, 50 ohm system):  $V_{DD}$  = 28Vdc,  $I_{DQ}$  = 150 mA, f = 500MHz

10:1, at 300W Pulsed CW No Device Degradation

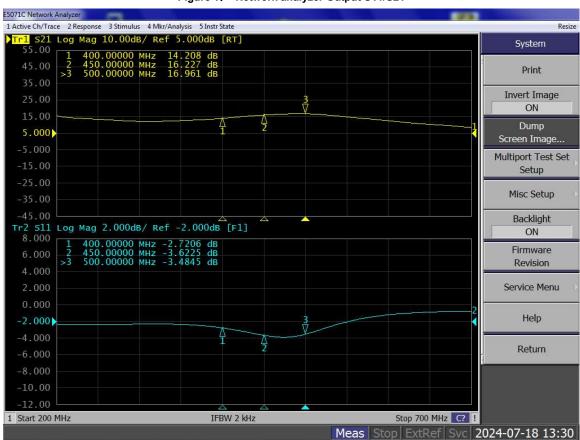
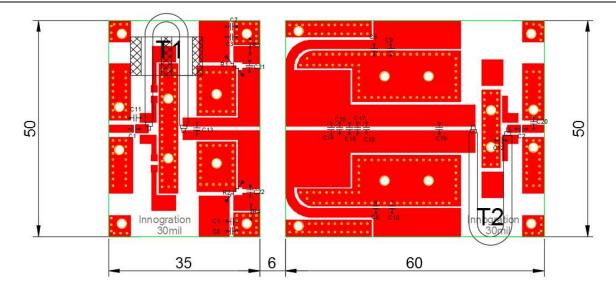


Figure 1: Network analyzer Output S11/S21

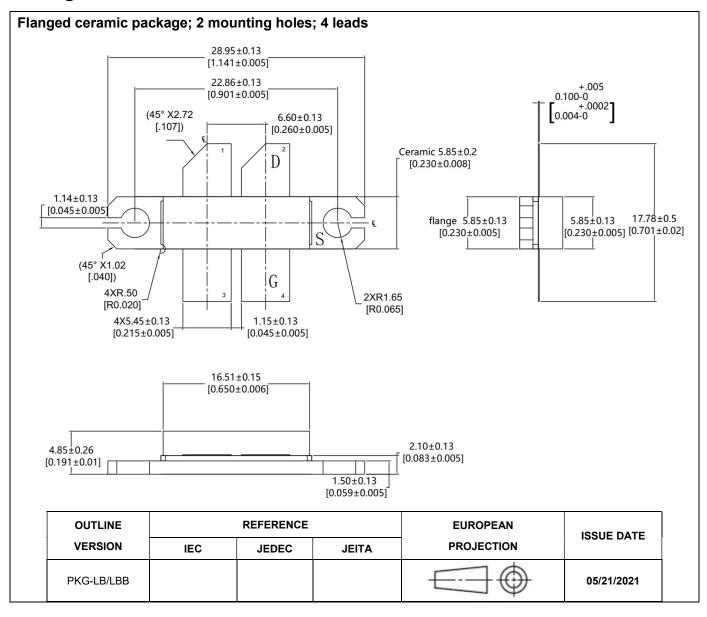
# **MX1530G LDMOS TRANSISTOR**



Component	Description	Suggestion
04.00	200-5	BEIJING YUANLU HONGYUAN ELECTRONIC
C1,C2	390pF	TECHNOLOGY CO., LTD.MQ301111
C3~C6	1000pF	BEIJING YUANLU HONGYUAN ELECTRONIC
C3~C6	ТОООРГ	TECHNOLOGY CO., LTD.MQ301111
C7~C11,C21,C22	10uF/100V	Ceramic Multilayer Capacitor
C12	4000-F	BEIJING YUANLU HONGYUAN ELECTRONIC
C12	1000pF	TECHNOLOGY CO., LTD.MQ101111
C13	45-5	BEIJING YUANLU HONGYUAN ELECTRONIC
C13	15pF	TECHNOLOGY CO., LTD.MQ301111
C14 C20	2.4pF	BEIJING YUANLU HONGYUAN ELECTRONIC
C14,C20	2.4ρε	TECHNOLOGY CO., LTD.MQ301111
C15	8.2pF	DLC70B
040	0.0.5	BEIJING YUANLU HONGYUAN ELECTRONIC
C16	8.2pF	TECHNOLOGY CO., LTD.MQ301111
C17	0.4=5	BEIJING YUANLU HONGYUAN ELECTRONIC
C17	9.1pF	TECHNOLOGY CO., LTD.MQ301111
C18	2 6nF	BEIJING YUANLU HONGYUAN ELECTRONIC
C10	3.6pF	TECHNOLOGY CO., LTD.MQ301111
C19	10pF	BEIJING YUANLU HONGYUAN ELECTRONIC
019	ΙΟΡΓ	TECHNOLOGY CO., LTD.MQ301111
R1,R2	200 Ω /½W	Pulg-in Resistor
R3,R4	10 Ω /1206	Chip Resistor
T.	RFSFBU-086-25 60mm	
T1	BN-61-2402	
T2	SFXF-35-3 45mm	
PCB		30Mil Rogers4350

# **MX1530G LDMOS TRANSISTOR**

### **Package Outline**



## **MX1530G LDMOS TRANSISTOR**

Document Number: MX1530G Product Datasheet V1.0

### **Revision history**

Table 5. Document revision history

Date	Revision	Datasheet Status
2024/7/19	Rev 1.0	Product Datasheet Creation

Application data based on HL-24-29

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